

# SOT2154-1(SC)

HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, 1.0 mm pitch, 6 mm x 6 mm x 1.9 mm body

17 December 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HQFN16
<b>Package style descriptive code</b>	HQFN (thermal enhanced quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	07-06-2021
<b>Manufacturer package code</b>	98ASA01812D

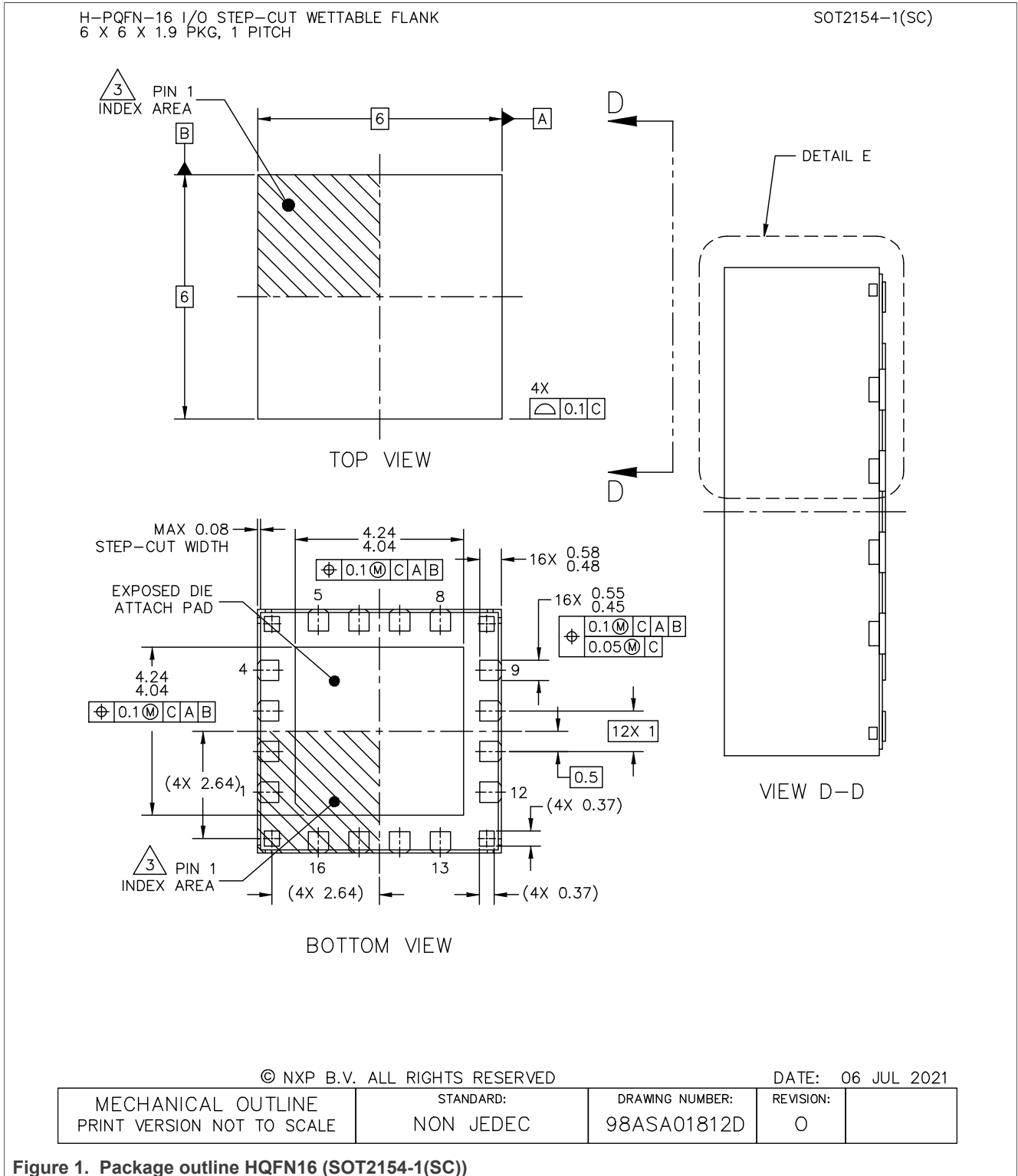
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
seated height	1.85	1.9	1.95	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	16	-	

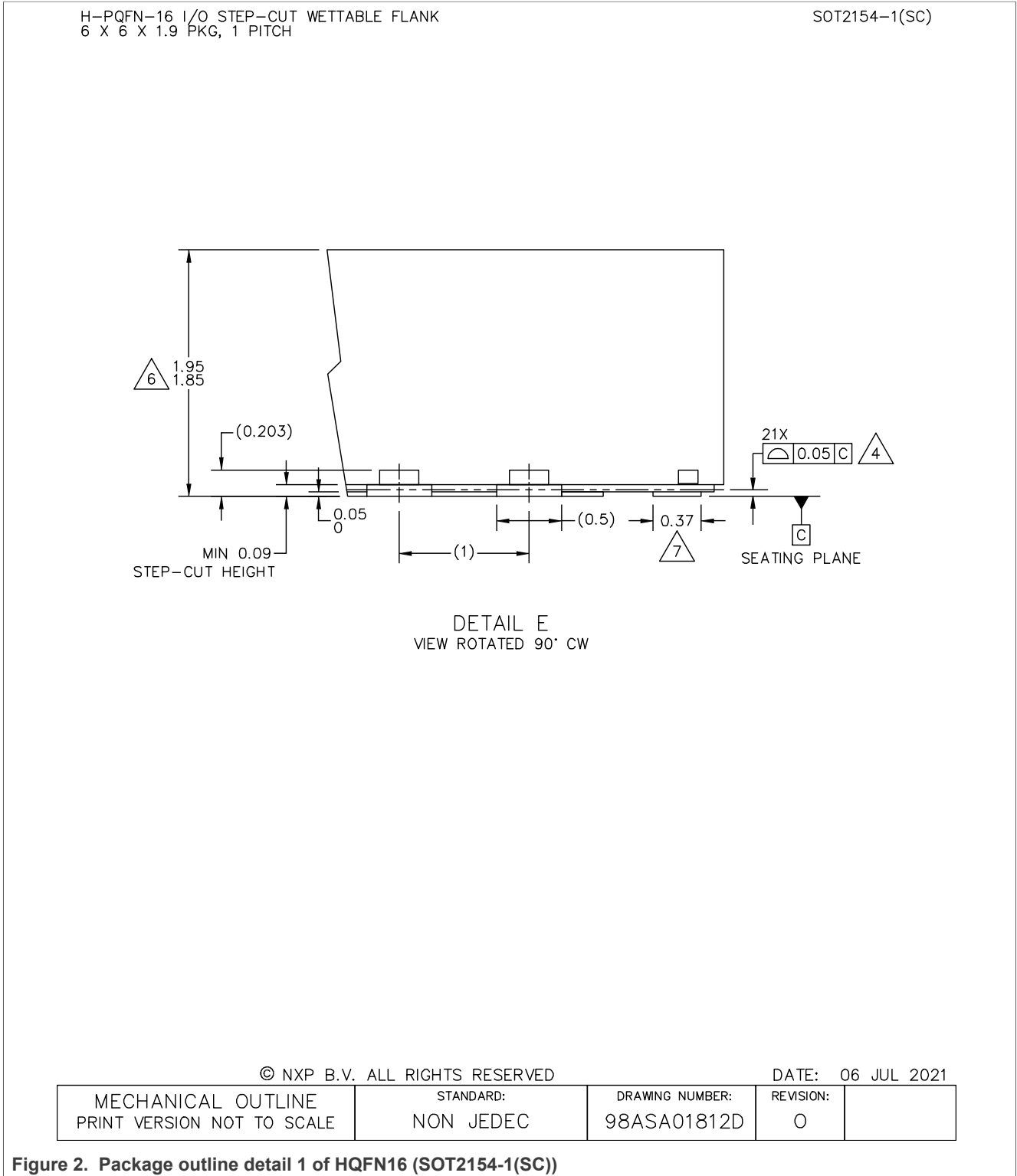


HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, 1.0 mm pitch, 6 mm x 6 mm x 1.9 mm body

2 Package outline



HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, 1.0 mm pitch, 6 mm x 6 mm x 1.9 mm body



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3 Soldering

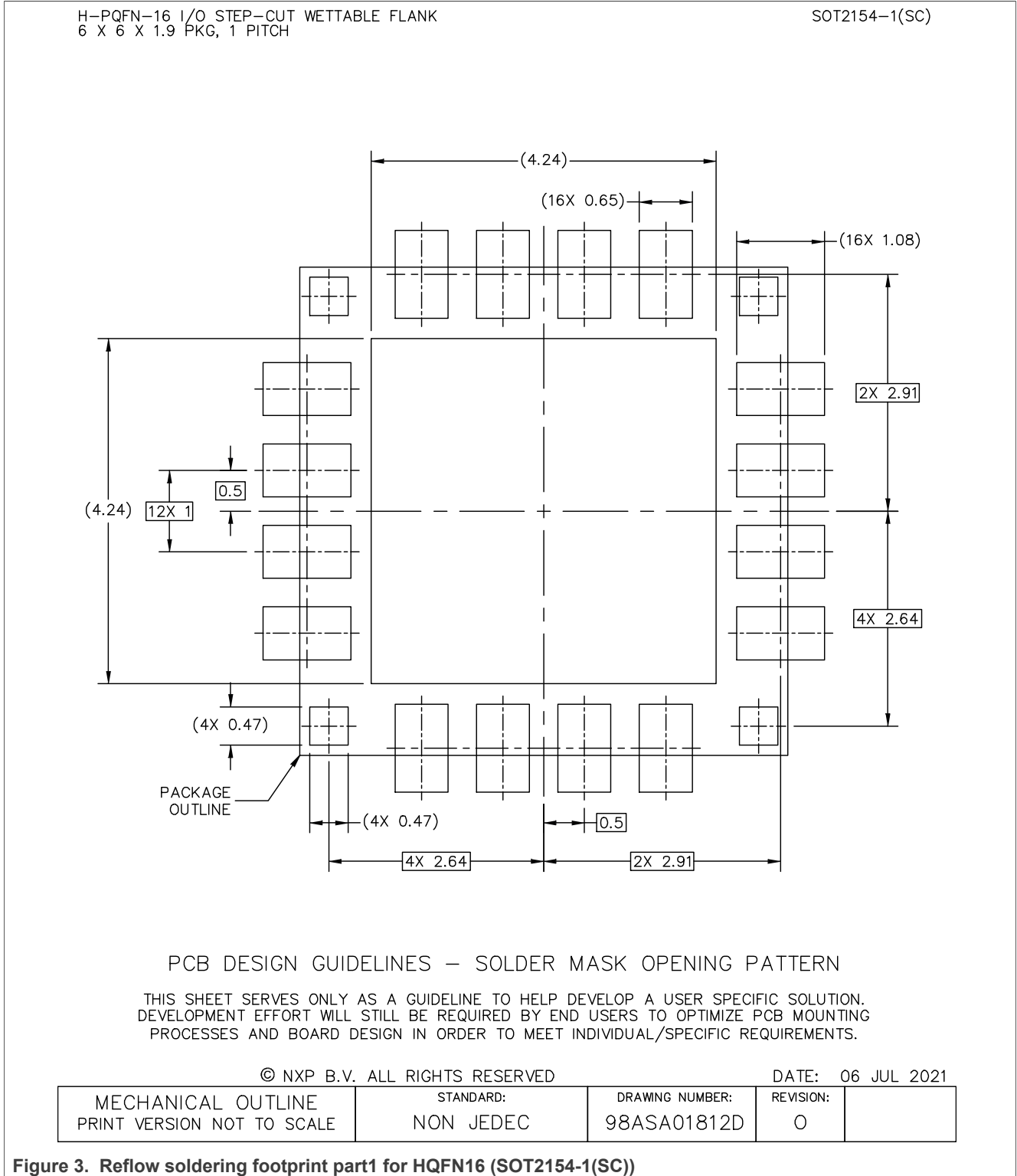


Figure 3. Reflow soldering footprint part1 for HQFN16 (SOT2154-1(SC))

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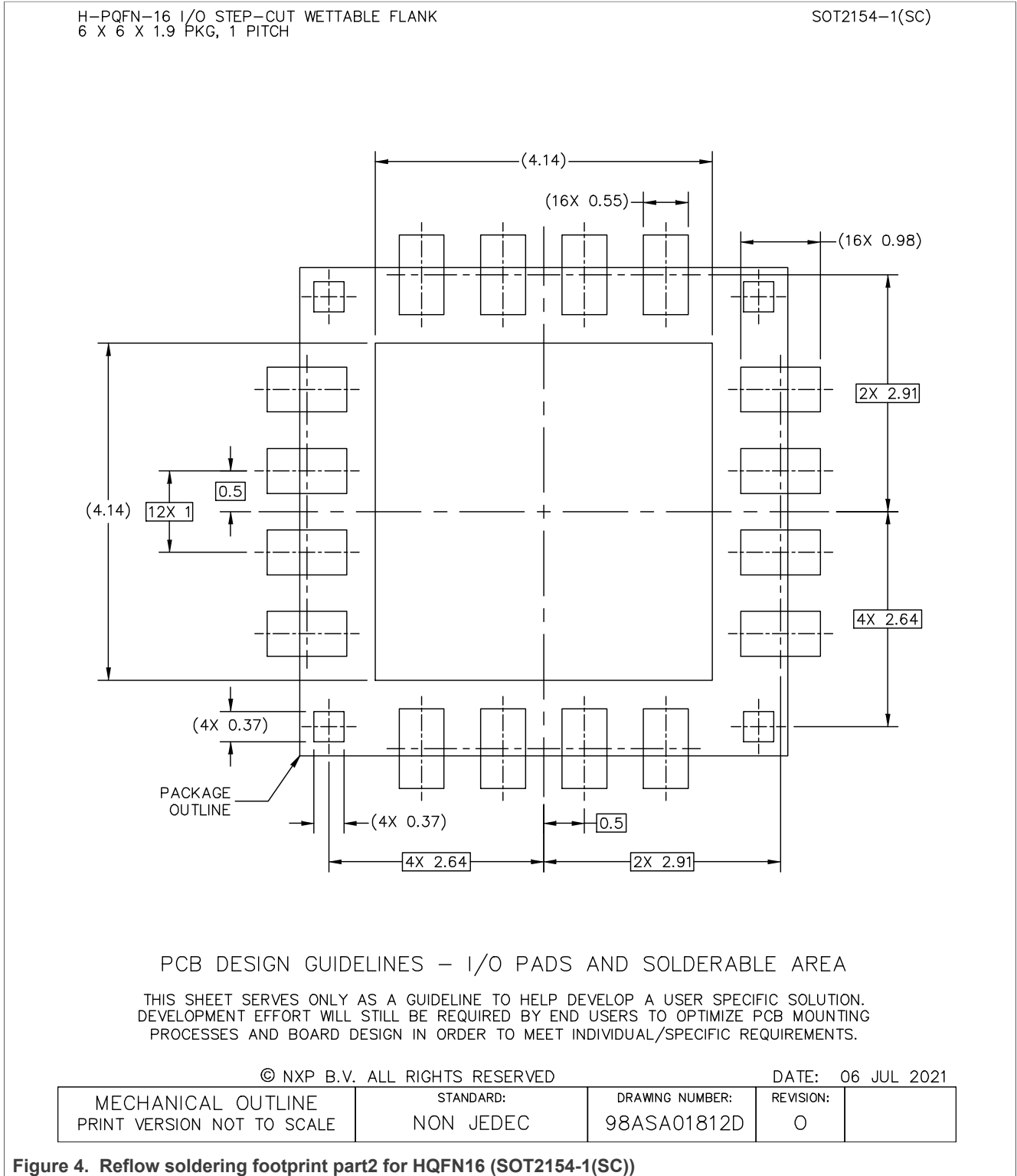


Figure 4. Reflow soldering footprint part2 for HQFN16 (SOT2154-1(SC))

HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, 1.0 mm pitch, 6 mm x 6 mm x 1.9 mm body

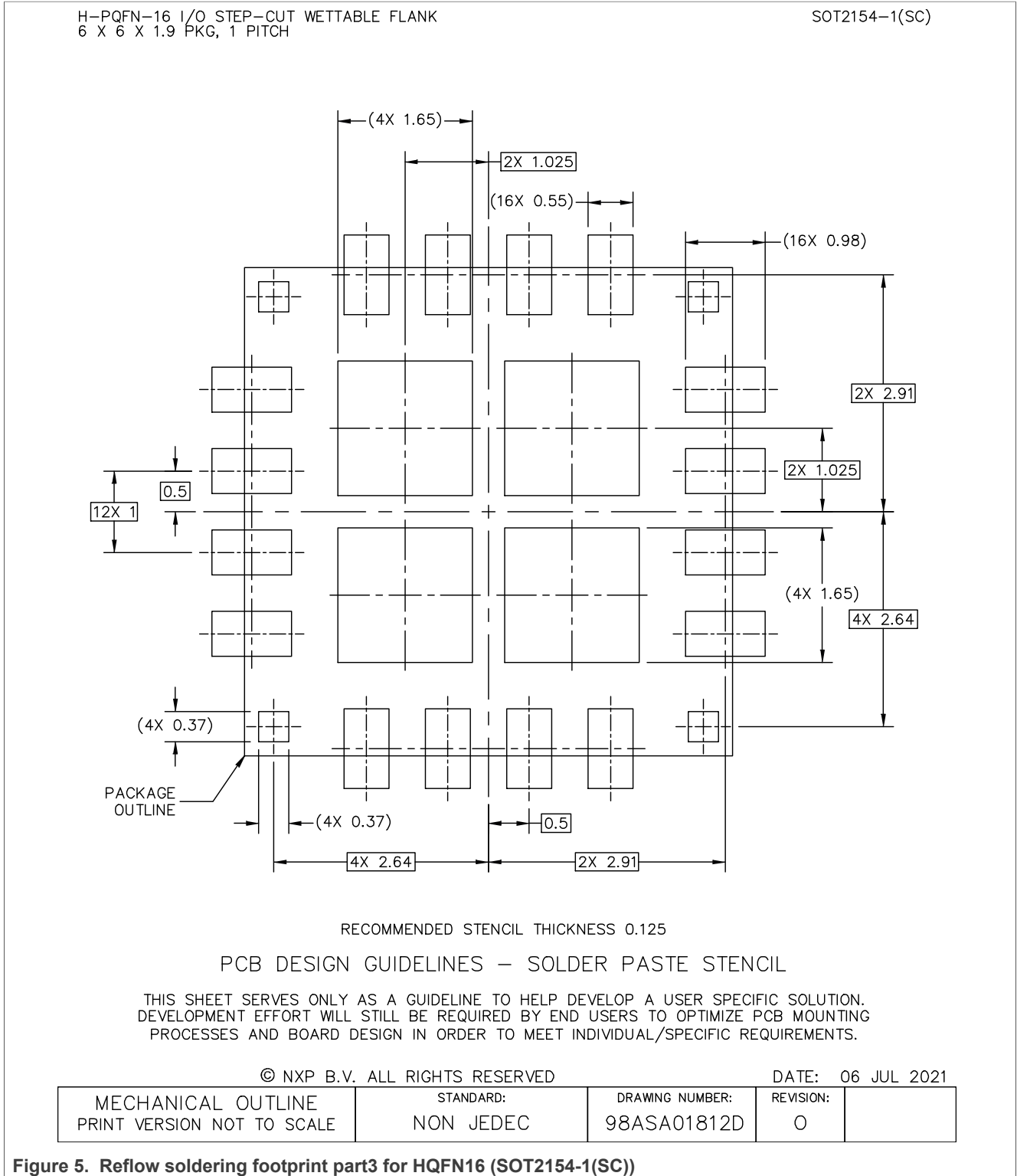


Figure 5. Reflow soldering footprint part3 for HQFN16 (SOT2154-1(SC))

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H-PQFN-16 1/0 STEP-CUT WETTABLE FLANK  
6 X 6 X 1.9 PKG, 1 PITCH

SOT2154-1(SC)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.
6. CONDUCTIVE METAL LAYER IS INCLUDED ON THE TOP SIDE SURFACE.
7. ANCHORING PADS.

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DATE: 06 JUL 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01812D	REVISION: 0	
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Figure 6. Package outline note HQFN16 (SOT2154-1(SC))

## 4 Legal information

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